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TMRC 2022

The 33rd Magnetic Recording Conference

August 29-31, https://tmrc22.sites.stanford.edu/

CALL FOR POSTER DIGESTS

The 33rd Magnetic Recording Conference will be held at Western Digital Milpitas campus on August 29-31, 2022. The focus of TMRC 2022 is **Solid State Magnetic Memory and Recording Technologies for >3 Tbits/in^2**

Approximately 36 invited papers of the highest quality will be presented orally at the conference and will later be published in the IEEE Transactions on Magnetics. Poster sessions will also be held following the oral sessions and will feature posters from the invited speakers and accepted contributed posters. Presenters of invited papers & contributed posters are encouraged for publication.

Topics of interest include:

- Solid State Memory – Devices and Applications
  - Spin Transfer Torque-Magnetic Random Access Memory (STT-MRAM)
  - MRAM– New Physics & Materials (MRAM architecture, VC-MRAM, SOT-MRAM, TI & 2D materials)
  - New Architectures and Applications for In-Memory and Near Memory Compute, Advanced Memory Bus Architectures, AI, ML and Neuromorphic Compute, 2.5 and 3D applications, Harsh environments
- Advanced Generation Recording Technologies
  - Heat Assisted Magnetic Recording (HAMR)
  - Microwave-Assisted Magnetic Recording (MAMR)
  - Alternative Magnetic Recording Technologies (EAMR, SMR, TDMR, HIMR, Heated-dot, Tape, All Optical Switching)
  - Advanced Magnetic Recording for > 3 Tbits/in^2 including Readers, Writers, Servo, Tribology, HDI and Signal Processing
- Recording and Memory Fundamentals (Metrology, Tooling, Device Processing, Materials, Recording Physics)

Poster contributors must send a 2-pages digest via email attachment to the Poster Co-Chairs by **June 13, 2022**. Details of the digest format requirements and a template can be found at the website https://tmrc22.sites.stanford.edu/digests. Notification of acceptance will be sent on **June 20, 2022**. All contributors are encouraged to submit a manuscript for publication in IEEE Trans. Magn. by August 2, 2022.

TMRC 2022 is sponsored by the IEEE Magnetics Society and co-sponsored by the Center for Magnetic Nanotechnology (Stanford), DSSC (CMU), CMRR (UCSD), MINT Center (Univ. of Minnesota), and the Computer Mechanics Laboratory (UC Berkeley).

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